

5 An improved method of attaching a semiconductor die to an organic substrate and an improved semiconductor package are herein disclosed. The die package comprises a die secured to a printed circuit board (PCB) with an adhesive tape. The adhesive tape may be of (single) or multi-layer construction. In one embodiment, a tri-layer tape is disclosed having a carrier layer sandwiched between two identical adhesive layers. In one embodiment, a method is disclosed utilizing a pressure sensitive, thermoset adhesive tape. In another embodiment, a method is
10 disclosed utilizing a B-stageable thermoset adhesive. In yet another embodiment, a method using a pressure sensitive adhesive is disclosed. In still yet another embodiment, a method is disclosed wherein the adhesive is a hybrid material having both thermoset and thermoplastic components.

"Express Mail" mailing label number: EL517792744US

Date of Deposit: August 29, 2000

This paper or fee is being deposited on the date indicated above with the United States Postal Service pursuant to 37 CFR 1.10, and is addressed to the Commissioner for Patents, Box Patent Application, Washington, D.C. 20231.